

APPLICATION DATA SHEET**Inventor Information**

Inventor One Given Name : Sion C.
Family Name : Quinlan
Postal Address Line One : 1, Lockstile Way
Postal Address Line Two : Goring on Thames
City : Oxon
Country of Residence : United Kingdom
Citizenship Country : United Kingdom

Inventor Two Given Name : Tim J.
Family Name : Bales
Postal Address Line One : 15 Derbyshire Green
Postal Address Line Two : Warfield
City : Bracknell
Country of Residence : United Kingdom
Citizenship Country : United Kingdom

Correspondence Information

Name Line One : Steven H. Arterberry, Esq.
Address Line One : DORSEY & WHITNEY LLP
Address Line Two : 1420 Fifth Avenue, Suite 3400
City : Seattle
State or Province : Washington
Postal or Zip Code : 98101
Telephone : 206-903-8800
Facsimile : 206-903-8820
E-Mail : patentseattle@dorseyllaw.com

Application Information

Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND
METHOD FOR ELECTRICALLY ISOLATING MODULES
Total Drawing Sheets : 3
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 30022/US/2
Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Continuity Information

This application is a : divisional of
>Application One : 10/057,205
Filing Date : January 25, 2002

Prior Foreign Application

Foreign Application One : 0126821.8
Filing Date : November 7, 2001
Country : United Kingdom
Priority Claimed : Yes

\\sefile03\files\ip\forms\patent\application data sheet.doc
4832-7702-3744\1 7/29/2003